

Device Selection Guide

Code	Chip Materials	Emitted Color	Resin Color
R7	AlGaInP	Dark-Red	– Water Clear
G6	AlGalnP	Brilliant Yellow Green	- Water Clear

Absolute Maximum Ratings (Ta=25)

Parameter	Symbol	Code	Rating	Unit	
Reverse Voltage	V_{R}		5	V	
Forward Current	I _F	R7	25		
		G6	25	- mA	
eak Forward Current (Duty 1/10 @1KHz)		R7	60		
	I _{FP}	G6	60	− mA	
Power Dissipation	Pd	R7	60		
		G6	60	− mW	
Electrostatic Discharge	ESD _{HBM}	R7	2000	V	
		G6	2000	- V	
Operating Temperature	T _{opr}		-40 ~ +85		
Storage Temperature	Tstg		-40 ~ +90		
Soldering Temperature	Tsol		Reflow Soldering : 26 Hand Soldering : 350	0 for 10 sec. for 3 sec.	

Expired Period: Forever



Electro-Optical Characteristics (Ta=25)

Parameter	Symbol	Code	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	R7	45.0		90.0	- mcd	
		G6	45.0		90.0		_
Viewing Angle	2θ _{1/2}			120		deg	_
Peak Wavelength	р	R7		639		- nm	_
		G6		575			
Dominant Wavelength	d	R7	625		637	- nm	I _F =20mA
		G6	568		575		
Spectrum Radiation Bandwidth		R7		20		- nm	
		G6		20			
Forward Voltage	.,	R7	1.7	2.0	2.4	- V	_
	V_{F}	G6 1.7 2.0 2.4	2.4	v			
Reverse Current	I _R -	R7			10	- μΑ	\/ -5\/
		G6			10		V _R =5V

Note:

1.Tolerance of Luminous Intensity: ±11%

2. Tolerance of Dominant Wavelength: ±1nm

LifecyclePhase:



Bin Range of Luminous Intensity

R7

Min.	Max.	Unit	Condition	
45.0	57.0			
57.0	72.0	mcd	I _F =20mA	
72.0	90.0			
Min.	Max.	Unit	Condition	
45.0	57.0			
57.0	72.0	mcd	I _F =20mA	
72.0	90.0			
	45.0 57.0 72.0 Min. 45.0 57.0	45.0 57.0 57.0 72.0 72.0 90.0 Min. Max. 45.0 57.0 57.0 72.0	45.0 57.0 mcd 57.0 72.0 mcd 72.0 90.0 Min. Max. Unit 45.0 57.0 57.0 72.0 mcd	

Typical Electro-Optical Characteristics Curves

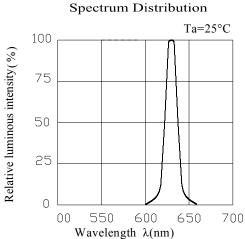
R7

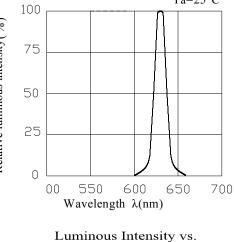
Relative luminous intensity (%)

1000

100

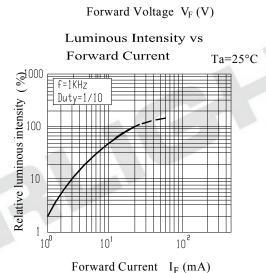
-40 -50 0 20 40 60 80





Ambient Temperature





Forward Current vs.

50

40

30

25 20

10

01.2

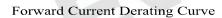
1.6

Forward Current IF (mA)

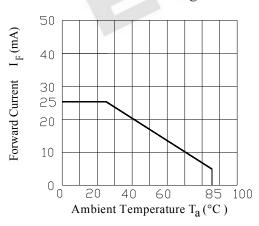
Forward Voltage
Ta=25°C

2.4

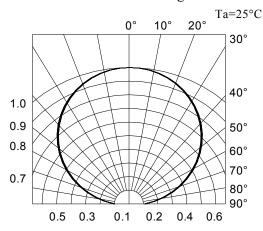
2.0



Ambient Temperature T_a(°C)

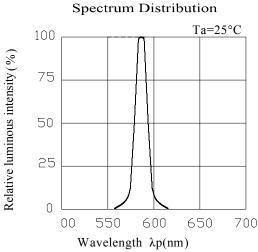


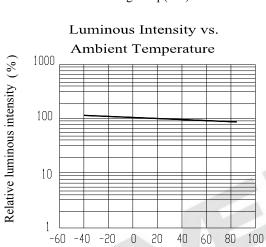




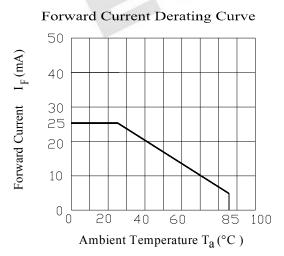
Typical Electro-Optical Characteristics Curves

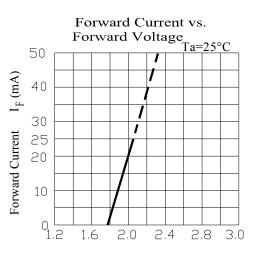
G6



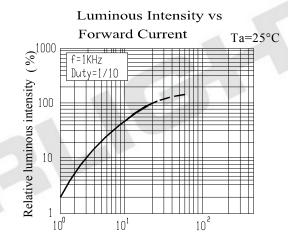


Ambient Temperature T_a(°C)

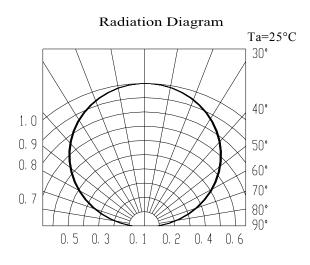




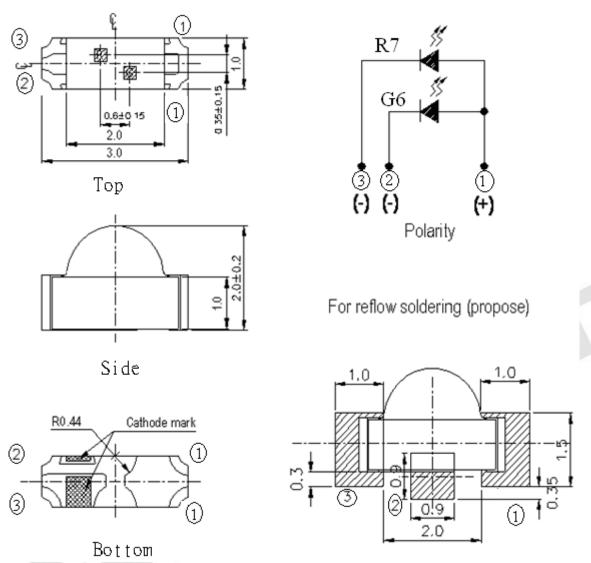
Forward Voltage $V_F(V)$



Forward Current I_F (mA)



Package Dimension



Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ±0.1mm. Unit = mm

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Label Explanation

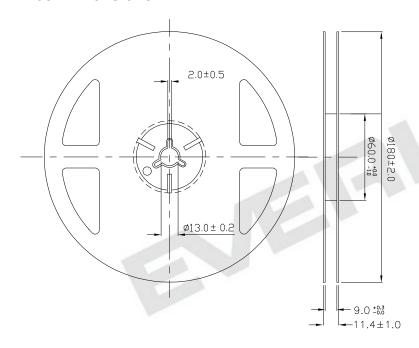


- CPN: Customer's Product Number
- P/N: Product Number QTY: Packing Quantity
- · CAT: Luminous Intensity Rank
- · HUE: Chromaticity Coordinates & Dom.

Wavelength Rank

- REF: Forward Voltage Rank
- · LOT No: Lot Number

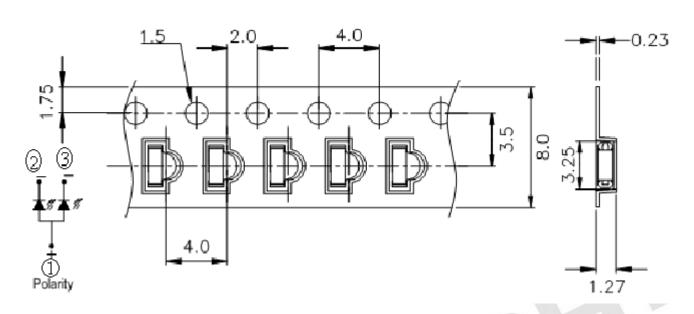
Reel Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

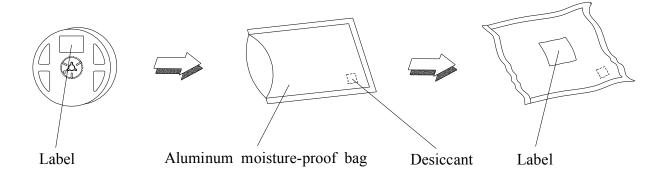
Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel

Progressive direction



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Moisture Resistant Packaging



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Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30 or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30 or less and 60% RH or less.

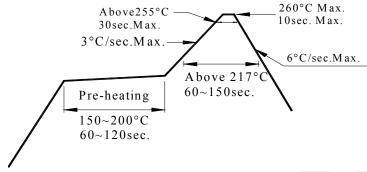
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: 60±5 for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



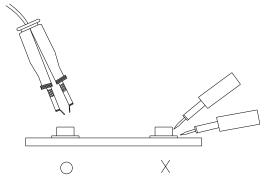
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350 for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Expired Period: Forever



Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.



Expired Period: Forever